

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application: Rajeev Joshi et al. Serial No.: 10/731,453 Filed: December 9, 2003 For: WAFER-LEVEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME	Confirmation No. 4432 Group Art Unit: 2891 Office: Zarnecke, David A.
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Mail Stop Non-Final Response
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION

In response to the Office Action mailed January 5, 2009, Applicant requests reconsideration of this application in light of the following amendments and remarks. Filed herewith is a petition for two-month extension of time to extend the period for response to this Office Action until June 5, 2009.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 7 of this paper.